## DIGI-KEY CORPORATION

Issue No.	:	151RJ000	07363
Date of Issue	:	June 01.20	007
Classification	:	New	□ Changed

## **PRODUCT SPECIFICATION FOR APPROVAL**

Product Description : Product Part Number :

: Thick Film Chip Resistors (RoHS)

: ERJXGNJ\*\*\*Y

Country of Origin : JAPAN Applications : Standar

: Standard electronic equipment

\*If you approve this specification, please fill in and sign the below and return 1 copy to us.

Approval No	1		
Approval Date	:		
Executed by	:		1
		(signature)	
Title	:		
Dept.	:		

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Outlinet			Space No.		
Subject Chip Resistor	PRODUCT SPECIFI	CATION FOR IMFORMATION	Spec. No. 151-SRJ-EX07A		
Part No.					
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	Ι	1			
Item	Rated value	Explanation			
	The rated voltage of each re	esistance should be calculated	from the equation		
Rated voltage &	below. And when the rated v	voltage exceeds the maximum	RCWV,		
Rated Continuous	the maximum RCWV should	-			
Working Voltage	Rated voltage = (Power rati	ng x Resistance Value) <sup>1/2</sup>			
	The maximum RCWV : 15V				
	The overload voltage should	be 2.5 times the rated voltage	e. And when		
Max.	the voltage exceeds the max	imum overload voltage, the va	lue shown below		
Overload Voltage	should be the maximum over	rload voltage.			
	The maximum overload volta	age: 30V			
Resistance	J : +/- 5%				
Tolerance					
Resistance Range	10 ohm – 1.0 M ohm (E-24	series)			
4. Explanation of Par	t Number		_		
<u>E</u> R (1)	<u>J X G N</u> (2)	$\frac{J}{(3)}  \frac{1}{(4)}  \frac{0}{(5)}$			
	Thick Film Chip Resistor				
. ,	Power : 0.4 mm x 0.2 mm, (	0.031 W			
	Restricted Flame Ret				
(3) Resistance Tole					
	Resistance Tolerance				
J	+/- 5%				
(4) Resistance Valu	e				
The first two	The first two digits are the significant figures of resistance value, and the last figure shows				
the number of	the number of zero following in ohm.				
(5) Packaging Conf	(5) Packaging Configuration				
	Code Packaging Configuration				
Y Ta	Y Taping (20,000pcs/reel)				

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5. Appearance & C	onstruction		
Item	Specification	Explanation	
	1. The resistive element shoul	ld be covered with protective	coating that don't
	fade easily. The surface of	coating should avoid uneven	ness, flaw, pinhole
	and discoloration.		
	2. The electrode should be pr	inted uniformly, as shown in t	the dimensions.
Appearance &	The plating should not fade	e easily, and should avoid une	evenness, flaw,
Construction	pinhole, projection and disc	-	
	3. The electrode should be co	onnected electrically, mechanic	ally to resistive
	element.		
	4. Dimensions of the substrate	e should be as in the list and	l it should not
	have chipping, flaw, flash and		

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As far as there shall not designation especially, the following tests and measurement shall be operated under the following conditions.

Normal temperature : 5 deg.C to 35 deg.C Normal humidity : 45 % to 85 %

Normal atmospheric pressure : 86 k Pa to 106 k Pa

6. Performance Specification

Item	Specification	Test Method (JIS-C5201-1)
DC resistance	DC resistance value shall be within the specified tolerance.	At 20 deg.C, 65%RH
Temperature coefficient of resistance (TCR)	10 ohm – 91 ohm : +/- 300 x 10 <sup>-6</sup> /deg.C 100 ohm – 1 M ohm : +/- 200 x 10 <sup>-6</sup> /deg.C	Natural resistance change per temperature degree centigrade. $TCR=(R_2-R_1)x10^6/R_1(t_2-t_1) \qquad (x10^{-6}/deg.C)$ $R_1 : Resistance value at referencetemperature (t_1)$ $R_2 : Resistance value at testtemperature (t_2)t_1 : 25 deg.C , t_2 : 125 deg.C$
Short time overload	∆R : +/-(2%+0.1 ohm)	Resistors shall be applied 2.5 times the rated voltage for 5 seconds. Max. overload voltage shall be 30V.
Intermittent overload	∆R : +/-(5%+0.1 ohm)	Resistors shall be subjected to 10000 cycles of 2.5 times the rated voltage applied for 1 second with pause of 25 seconds between tests. Max. overload voltage shall be 30V.

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7. Machinery chara	cteristic	1	
ltem	Specification	Test Method (JIS-C	5201-1)
Bending	No mechanical damage.	Substrate : Glass epoxy (t=1 Span : 90mm Bending distance : 3mm (10 <test pattern=""> 0.2 0.2 0.2 0.2</test>	
strength	∆R : +/-(1%+0.05 ohm)		
Solderability	Termination should be covered uniformly with solder (Min. 95% coverage)	Resistors shall be dipped in bath at 235 deg.C +/- 5 deg +/- 0.5 second. Flux shall be the surface of termination w solvent.	g.C for 2 seconds e removed from
Resistance to soldering heat	∆R : +/-(1%+0.05 ohm)	Resistors shall be dipped in bath at 270 deg.C +/- 3 deg +/- 1 second.	
Resistance to vibration (Low frequency)	ΔR : +/-(1%+0.05 ohm)	Resistors shall be subjected vibration having as double a mm in 3 directions perpendi- for 2 hours each. (6 hours in The vibration frequency shall uniformly from 10 Hz to 55 H to 10 Hz traversing for 1 min	mplitude of 1.5 cular one another n total) I be varied Hz, and return
Resistance to	Without distinct deformation in appearance	Solvent solution : Isopropyl alcohol (1)Dipping 10 +/- 1 hours, dry in room condition for 30 +/- 10 minutes.	
solvent	ΔR : +/-(0.5% +0.05 ohm)	(2)Ultrasonic wave washing : (0.3W/cm <sup>2</sup> ,28 Dry in room condition for	8kHz)

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## 8. Environmental test

Item	Specification	Test Method (JIS-C5201-1)	
Low temperature exposure	∆R : +/-(1%+0.05 ohm)	Resistors shall be exposed at -55 deg.C +/- 3 deg.C with no load for 1000 hours +48/-0 hours.	
High temperature exposure	∆R : +/-(1%+0.05 ohm)	Resistors shall be exposed at 125 deg.C +/- 3 deg.C with no load for 1000 hours +48/-0 hours.	
Temperature cycling	∆R : +/-(1%+0.05 ohm)	Resistors shall be tested for 5 cyclescontinuously in accordance with the followingduty cycle.StepTemperature (deg.C)Time (min.)1-55 +/-3302Room temperatureMax. 33+125 +/-3304Room temperatureMax.3	
Humidity (Steady state)	∆R : +/-(1%+0.05 ohm)	Resistors shall be exposed at 60 deg.C +/- 2 deg.C and 90% to 95% relative hummidity in a humidity test chamber for 1000 hours +48/-0 hours.	
Load life	ΔR : +/-(3%+0.1 ohm)	Resistors shall be operated at DC rated voltage (1.5 hours "ON", 0.5 hours "OFF") for 1000 hours +48/-0 hours in a test chamber controlled at 70 deg.C +/-2 deg.C.	
Load life in humidity	∆R : +/-(3%+0.1 ohm)	Resistors shall be operated at DC rated voltage (1.5 hours "ON", 0.5 hours "OFF") for 1000 hours +48/-0 hours in a test chamber controlled at 60 deg.C +/- 2 deg.C and at 90 % to 95% in relative hummidity.	

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9. Common precautions in handling resistors	
Notice for use	
(1) This specification shows the quality and performance of a unit component.	Before adoption,
be sure to evaluate and verify the product mounting it in your product.	
(2) We take no responsibility for troubles caused by the product usage that is this specification.	not specified in
(3) Use fail-safe design and ensure safety by carrying out the following items is forecast that the failure of the product gives serious damage to someth human life, for instant in traffic transportation equipment (trains, cars, traffi equipment, etc.), medical equipment, aerospace equipment, electric heating combustion and gas equipment, rotating equipment, disaster and crime pre equipment.	ing important like c signal g appliances,
*Ensure safety as the system by setting protective circuits and protective of *Ensure safety as the system by setting such redundant circuits as do not a single failure.	
<ul><li>(4) When a dogma shall be occurred about safety for this product, be sure to operate your technical examination.</li></ul>	inform us rapidly,
(5) The product is designed to use in general standard applications of general equipment (AV products, household electric appliances, office equipment, in communication equipment, etc.); hence, it do not take the use under the f environments into consideration.	nformation and
Accordingly, the use in the following special environments, and such environments, and such environments, and such environments are such as a such environment of the product; prior to use, verify the such as a such environment of the product; prior to use, verify the such as a such as	
<ol> <li>Use in liquids such as water, oil, chemical, and organic solvent.</li> <li>Use under direct sunlight, in outdoor or in dusty atmospheres.</li> </ol>	
<ul> <li>3) Use in places full of corrosive gases such as sea breeze, Cl<sub>2</sub>, H<sub>2</sub>S, NH</li> <li>4) Use in environment with large static electricity or strong electromagnetic</li> <li>5) Where the product is close to a heating component, and where an infla a polyvinyl chloride wire is arranged close to the product.</li> <li>6) Where the resistor is sealed or coated with resin, etc.</li> </ul>	c waves.
<ul><li>7) Where water or a water-soluble detergent is used in cleaning free sold cleaning after soldering (Pay particular attention to soluble flux.)</li><li>8) Use in such a place where the product is wetted due to dew condensations</li></ul>	-
(6) If transient load (heavy load in a short time) like pulse is expected to be a evaluation and confirmation test with resistors actually mounted on your ow the load of more than rated power is applied under the load condition at	wn board. When
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<ul> <li>the product shall be u</li> <li>(7) Halogen type (Chloring recommended as the</li> <li>(8) When soldering with s of the chip resistor w at high temperature, s 350 deg.C)</li> <li>(9) Avoid physical shock t pliers or tweezers) as resistor's performance</li> <li>(10) Avoid immersion of c immersion is confirm</li> <li>(11) This resistance may In case of handling to Environment where (Recommendation is connecting surface)</li> </ul>	hip resistor in solvent for long time. Use solvent afted	idvance. is not tors. er touch the body ng iron with a tip ls or less up to tool (a pair of or and may affect

Storage Method

If the product is stored in the following environments and conditions, the performance and solderability may be badly affected, avoid the storage in the following environments.

- (1) Storage in places full of corrosive gases such as sea breeze,  $Cl_2$ ,  $H_2S$ ,  $NH_3$ ,  $SO_2$ , and  $NO_X$ .
- (2) Storage in places exposed to direct sunlight.
- (3) Storage in places outside the temperature range of 5 deg.C to 35 deg.C and humidity range of 45 %RH to 85 %RH.
- (4) Storage over a year after our delivery (This item also applies to the case where the storage method specified in item (1) to (3) has been followed.).

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<ol> <li>Laws and Regulations         <ol> <li>This product has not been manufactured with any ozone-depleting chemical controlled under the Montreal Protocol.</li> <li>This product complies with the RoHS Directive (Restriction of the use of certain Hazardous Substances in electrical and electronic equipment (DIRECTIVE 2002/95/EC)).</li> <li>All materials used in this part are registered material under the Law Concerning the Examination and Regulation of Manufacturs, etc. of Chemical substances.</li> <li>All the materials used in this part contain no brominated materials of PBBO<sub>S</sub> or PBB<sub>S</sub> as the flame-retardant.</li> <li>If you need the notice by letter of "A preliminary judgement on the Laws of Japan foreign exchange and Foreign Trade control", be sure to let us know.</li> </ol> </li> </ol>		
12. Production site Country : Japan Plant : Panasonio	c Electronic Devices Fukui Co., Ltd.	



(1) Minimum Bending Radius

When Carrier tape shall be bent by Minimum Bending Radius (15mm), no defection of chip and no break of carrier tape. However minimum bending radius shall be tested for 1 time.

(2) Resistance to climate of top tapeWhen it shall be exposed at 60 deg.C, 90 to 95 %RH for 120 hours, no exfoliation of top tape.

